

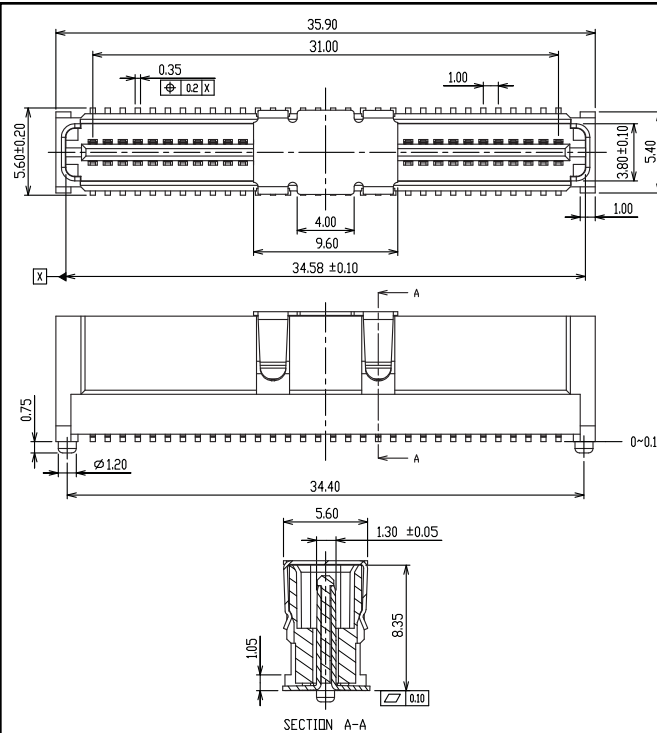


Fig. 1

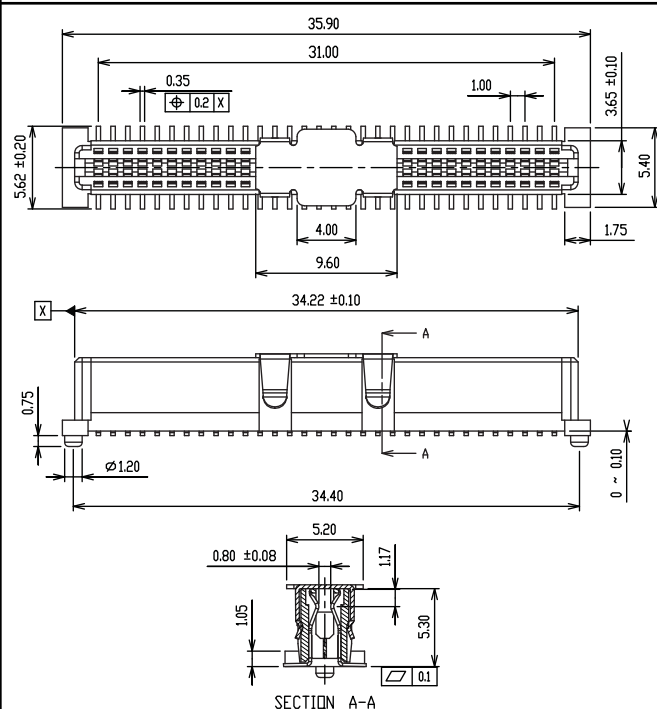
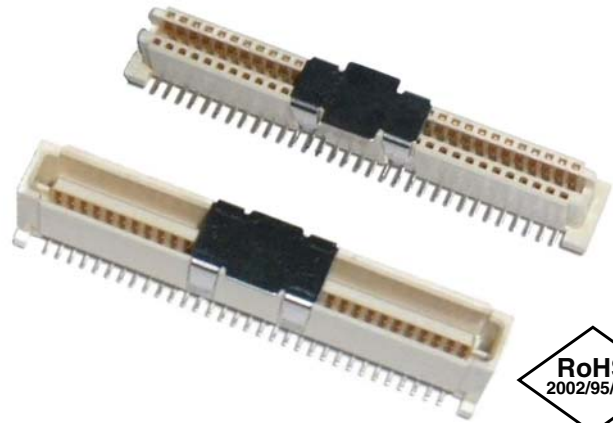
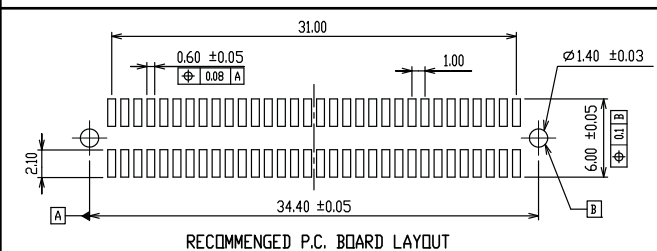


Fig. 2



RoHS
2002/95/EC

Features:

- 64 Position Mezzanine connectors for board stacking.
- 1 mm Centerline high density packaging.
- Mated connector board stacking height of 10 mm.
- Conforms to EIA-700 AAAB for IEEE 1386 applications.
- Suitable for "lead free" reflow soldering (260° C peak).
- Tape & Reel packaged per EIA-783 (56 mm wide; 16 mm pitch).

Ordering Information:

Figure 1: 1mm Surface Mount Male Connector

891-10-064-30-120000

Packaging: 400 Parts per 13" reel

Figure 2: 1mm Surface Mount Female Connector

893-43-064-30-420000

Packaging: 600 Parts per 13" reel

Specifications:

Materials:

Terminals & Contacts: Phosphor Bronze
Plating: Contact area - 30 μ " Gold over nickel
Solder Terminals - 75 μ " Tin over nickel
Vacuum Cap: Stainless Steel
Insulator Material: High temperature glass filled LCP, rated UL 94V-0

Ratings:

Current: (30° C Temperature Rise): 0.5 A max., all circuits wired in series (1.0A max., five adjacent circuits wired in series)
Voltage: 250V AC (RMS) (contact to contact)
Operating Temperature range: -55° C - +85° C

Electrical:

Contact resistance: 30m Ω max.
Insulation resistance: 1,000 M Ω min.
Dielectric Withstanding Voltage: 250V AC for one minute@sea level

Mechanical:

Vibration: No discontinuity > 1 μ s per MIL-STD 202, Method 201
Physical Shock: No discontinuity > 1 μ s per EIA 364-27 Test Condition H
Durability: 100 Cycles min. per EIA 364-09
Mating Force: 60 g/terminal max. per EIA 364-13
Separation Force: 23 g/terminal min. per EIA 364-13
Contact Retention Force: .4Kg min. per EIA 364-35

Environmental:

Thermal Shock: Per EIA 364-32, Test Condition I
Humidity: Test conditions - Ambient temp. 40 $\pm$ 2°C; Relative humidity: 90 - 95%; Duration: 96 Hrs.
Post Humidity inspection - 1. No damage
2. Contact resistance change < 15 m Ω
3. Insulation Resistance: 100 M Ω min.
Solderability: Per EIA 364-52 Category 2